

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

Generic Copy

08 Dec 2009

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16377

TITLE: Fab Transfer of PS5LVTI1 from ON Semiconductor Piestany to ONC25BCD ON Semiconductor Gresham

PROPOSED FIRST SHIP DATE: 08 Mar 2010

AFFECTED CHANGE CATEGORY(S): On Semiconductor Wafer Fab Site

AFFECTED PRODUCT DIVISION(S): SPG

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Angela Tam <Angela.Tam@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Matt Kas < Matt.Kas@onsemi.com >

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the Final Process Change Notification to Initial Process Change Notice #16249. The IPCN can be found at www.onsemi.com.

On Semiconductor is pleased to announce the fab transfer of PS5LVTI1 technology from ON Semiconductor, Piestany Fab to On Semiconductor, Gresham Fab on SUS616x device family.

Upon the expiration of this FPCN, the affected devices can have die sourced from the newly qualified fab (On Semiconductor, Gresham) and the existing fab On Semiconductor, Piestany. All devices will continue to meet datasheet performance and in compliance to the ON Semiconductor's quality standards.

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RELIABILITY DATA SUMMARY:

Qual Vehicle: NCP360SNAFT1G Test: High Temperature Operating Life Conditions: Temp: 115°C; Duration: 504 hours

Results: 0/80

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no significant change in electrical parametric performance. Electrical data is available upon request.

CHANGED PART IDENTIFICATION:

The parts listed under the affected parts list with date code WW10 2010 or later can have die sourced from On Semiconductor, Aizu or the existing wafer foundry.

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AFFECTED DEVICE LIST

NUS6160MNTWG SUS6160MNTWG SUS6162MNTWG

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